

I CLAIM:

1. A component mounting circuit board comprising:
a circuit pattern including a plurality of electrically
5 conductive plates;
an inner electrical component electrically connected to the
circuit pattern; and
a resin molded section made of a resin by way of molding
so as to cover the circuit pattern and the inner electrical
10 component, the resin molded section having an opening allowing
an outer electrical component located outside the resin molded
section to be connected to the circuit pattern therethrough.
2. The component mounting circuit board according to claim
15 1, wherein the resin molded section is made of an epoxy resin.
3. The component mounting circuit board according to 1,
wherein the circuit pattern includes a portion corresponding to
the inner electrical component and provided with a thicker
20 portion thicker than a remaining portion.
4. The component mounting circuit board according to claim
1, wherein the circuit pattern includes a portion corresponding
to the inner electrical component and provided with an exposed
25 portion exposed outside the resin molded section.
5. The component mounting circuit board according to claim
1, further comprising a metal member embedded in the resin molded

1, further comprising a metal member embedded in the resin molded section so as to be located to correspond to a portion of the inner electrical component and electrically insulated from the circuit pattern, the metal member being provided with an exposed portion exposed outside the resin molded section.

6. The component mounting circuit board according to claim 1, further comprising a metal member embedded in the resin molded section so as to be located at a portion corresponding to the inner electrical component, the metal member being discrete from the circuit pattern.

7. The component mounting circuit board according to claim 1, further comprising a support provided on the resin molded section to support the outer electrical component.

8. The component mounting circuit board according to claim 1, further comprising a terminal provided on the circuit pattern so as to project outside the resin molded section.

9. The component mounting circuit board according to claim 1, wherein the inner electrical component is connected to the circuit pattern by wire bonding.

10. The component mounting circuit board according to claim 1, wherein the outer electrical component is soldered to a portion of the circuit pattern corresponding to the opening.

11. A component mounting circuit board which is incorporated in a microwave oven and on which a power supply circuit for driving a magnetron, a switching circuit, etc. are mounted, the circuit board comprising:

- 5 a circuit pattern including a plurality of electrically conductive plates;
- an inner electrical component electrically connected to the circuit pattern; and
- a resin molded section made of a resin by way of molding
- 10 so as to cover the circuit pattern and the inner electrical component.

12. The component mounting circuit board according to claim 11, wherein the resin molded section includes an opening used

15 when an outer electrical component located outside the resin molded section is connected to the circuit pattern.

13. A method of making a component mounting circuit board comprising the steps of:

- 20 electrically connecting an inner electrical component to a circuit pattern including a plurality of electrically conductive plates;

 covering the circuit pattern and the inner electrical component with a resin, thereby forming a resin molded section

25 having an opening; and

 electrically connecting an outer electrical component located outside the resin molded section through the opening.